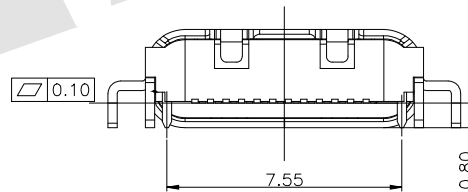
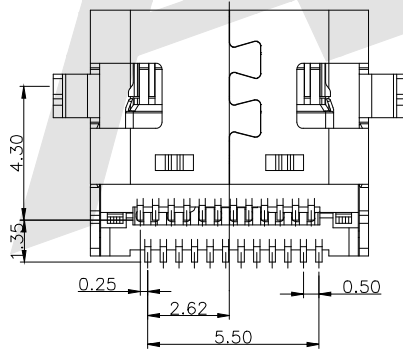
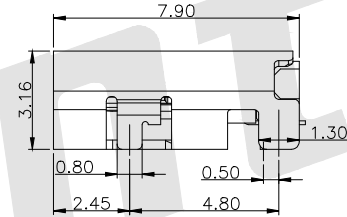
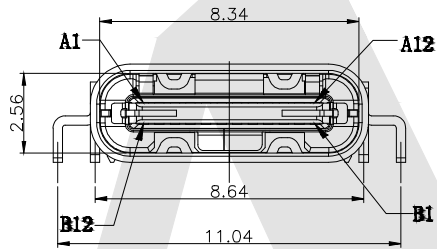
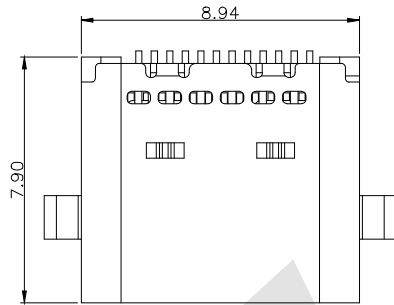


HSF

RoHS



SPECIFICATIONS:

- 1. MOLDING: LCP UL94 V-0
- CONTACT: COPPER ALLOY
- GOLD PLATED MIN ON CONTACT AREA 100U"
- MIN TIN (LEAD FREE) ON SOLDER AREA
- SHELL: SUS304-H, T+0.30±0.03MM
- 50U" NICHEL PLATING OVER ALL
- SHILD: SUS304-H, T+0.12±0.03MM
- 2. MECHANICAL:
- INSERTION: 5N-20N
- EXTRACTION: 8-20N AFTER TEST
- DURABILITY: 10000CYCLES
- 3. ELECTRICAL:
- CURRENT: 5A FOR VBUS
- 1.25A FOR GND PIN
- 0.25A FOR OTHER
- VOLTAGE: 20V MAX
- WITHSTANDING VOLTAGE: 100V AC R. M. S
- CONTACT RESISTANCE: 40MΩ MAX
- INSULATION RESISTANCE: 100MΩ MIN
- 4. ENVIRONMENTAL
- TEMPERATURE RANGE -25° C ~ +85° C

U3. 1FM08 - S - L - X - X - X

① ② ③ ④ ⑤ ⑥

- ① Series No:
- ② Shell Material: S:stainless steel
- ③ Insulator Material: L:LCP
- ④ Contact Material: B:Brass P:phosphor copper
- ⑤ Contact Plating: G0: Gold flash G1: 3u" Gold G2: 5u" Gold G3: 10u" Gold G4: 15u" Gold G5: 30u" Gold
- ⑥ Packing: A:Tray B:Bag C:Tube D:Tape&Reel

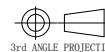
Unless Otherwise specified tolerance
 X. ±0.35 X.XX: ±0.20
 X.X: ±0.25 X.XXX: ±0.15



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[Http://www.antenk.com](http://www.antenk.com)
 E-mail:sales@antenk.com

SCALE: As Shown UNIT: mm
 DRAW Lv Xun Hua DATE 20/08/2019
 CHECK BobYang DATE 20/08/2019

TITLE: USB 3.1 C TYPE COUNTERSINK 0.80 SMT FINISHED
 PRODUCT 7.90L PCB LAYOUT

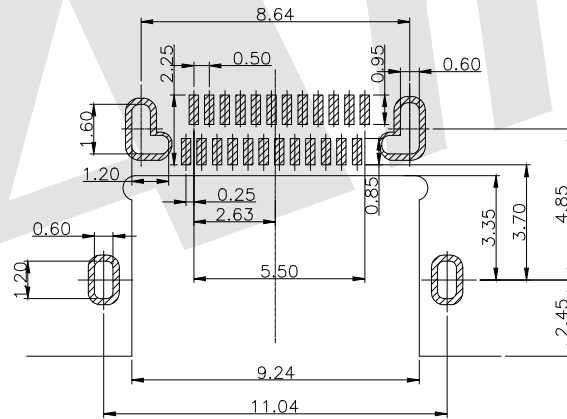
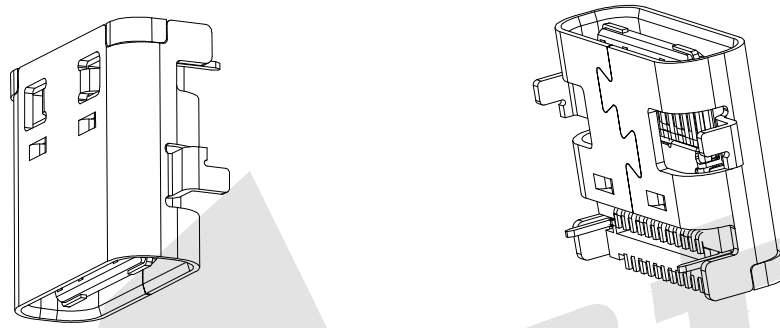


DRAWING NO: U3. 1FM08-SLXXX
 PRODUCT NO: U3. 1FM08-SLXXX

REV	DESCRIPTION	DATE



USB TYPE FULL-FEATURED RECEPTACLE INTERFACE PIN ASSIGNMENTS



PCB LAYOUT (RECOMMENDED)
(Tol: ±0.05)

PIN	Signal Name	Description	B13	Signal Name	Description
A1	GND	Groundreturn	B12	GND	Groundreturn
A2	SSTXP1	Positive half of first SuperSpeed TX differential pair	B11	SSRXp1	Positive half of first SuperSpeed RX differential pair
A3	SSTXn1	Negative half of first SuperSpeed TX differential pair	B10	SSRXn1	Negative half of first SuperSpeed RX differential pair
A4	VBUS	Bus Power	B9	VBUS	Bus Power
A5	CC1	Configuration Channel	B8	SBU2	Sideband Use (SBU)
A6	Dp1	Positive half of the USB 2.0 differential pair-Position 1	B7	Dn2	Negative half of the USB 2.0 differential pair-Position 2
A7	DN1	Positive half of the USB 2.0 differential pair-Position 2	B6	Dp2	Positive half of the USB 2.0 differential pair-Position 2
A8	SBUS	Sideband Use (SBU)	B4	CC2	Configuration Channel
A9	VBUS	Bus Power	B4	VBUS	Bus Power
A10	SSRXn2	Negative half of second SuperSpeed TX differential pair	B3	SSTXn2	Negative half of second SuperSpeed TX differential pair
A11	SSRXp2	Positive half of second SuperSpeed TX differential pair	B2	SSTXp2	Positive half of second SuperSpeed TX differential pair
A12	GND	Ground return	B1	GND	Ground return

Unless Otherwise specified tolerance
 X. ±0.35 X.XX: ±0.20
 X.X: ±0.25 X.XXX: ±0.15



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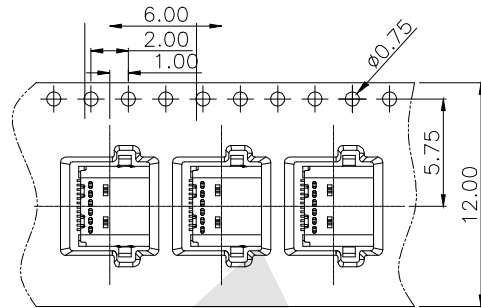


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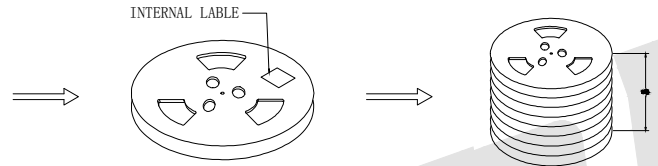
REV	DESCRIPTION	DATE

HSF

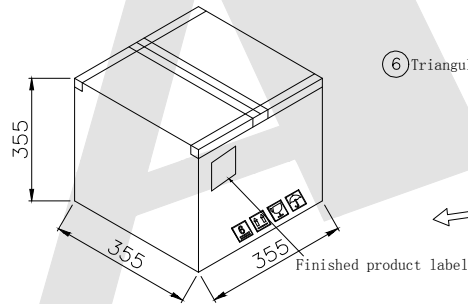
RoHS



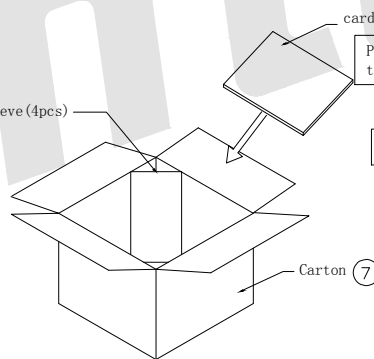
① Schematic diagram of product loading into carrier tape



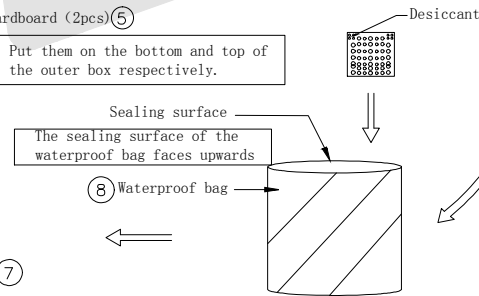
② Schematic diagram of reel labeling
③ Schematic Diagram of Stacking 10 Dishes of Products



⑥ Schematic Diagram of Outer Box Sealing



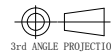
⑤ Schematic Diagram of Products Entering Outer Boxes



④ Put 7 plates of products into waterproof bags.

Unless Otherwise specified tolerance
X. ±0.35 X.XX: ±0.20
X.X: ±0.25 X.XXX: ±0.15

SCALE: As Shown UNIT: mm
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